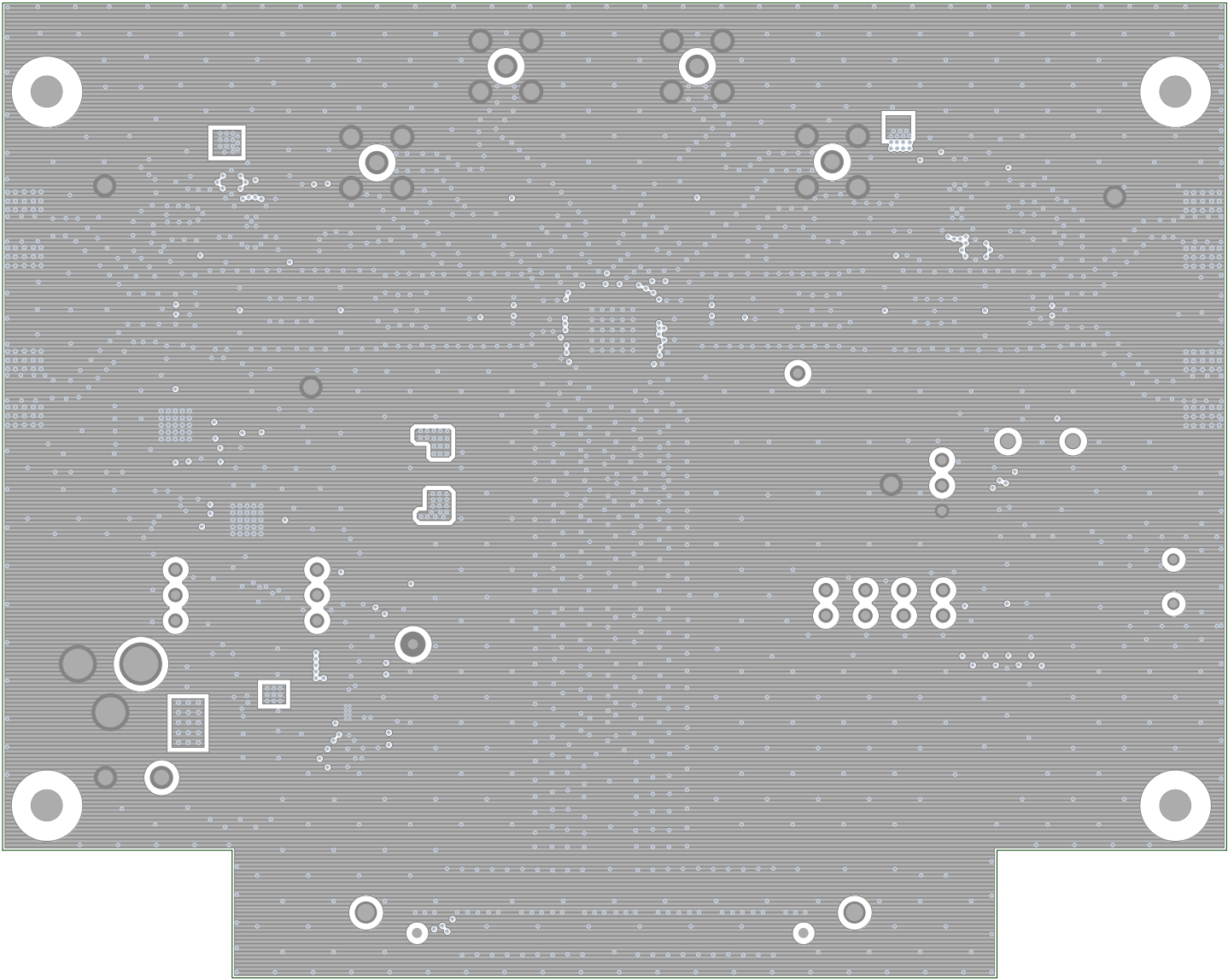


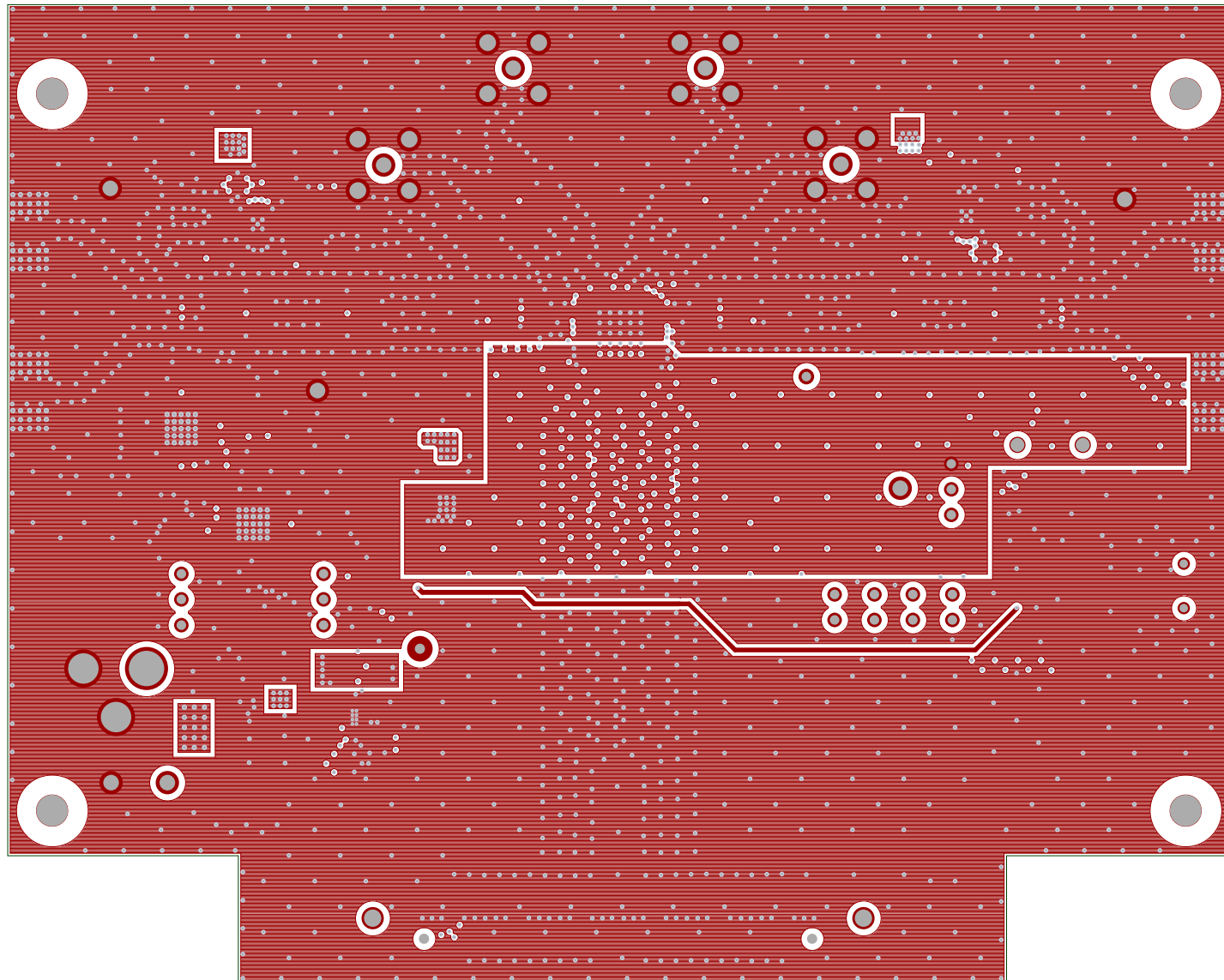
TEXAS INSTRUMENTS  
ADC32XXEVM REV C

SILKSCREEN TOPSIDE



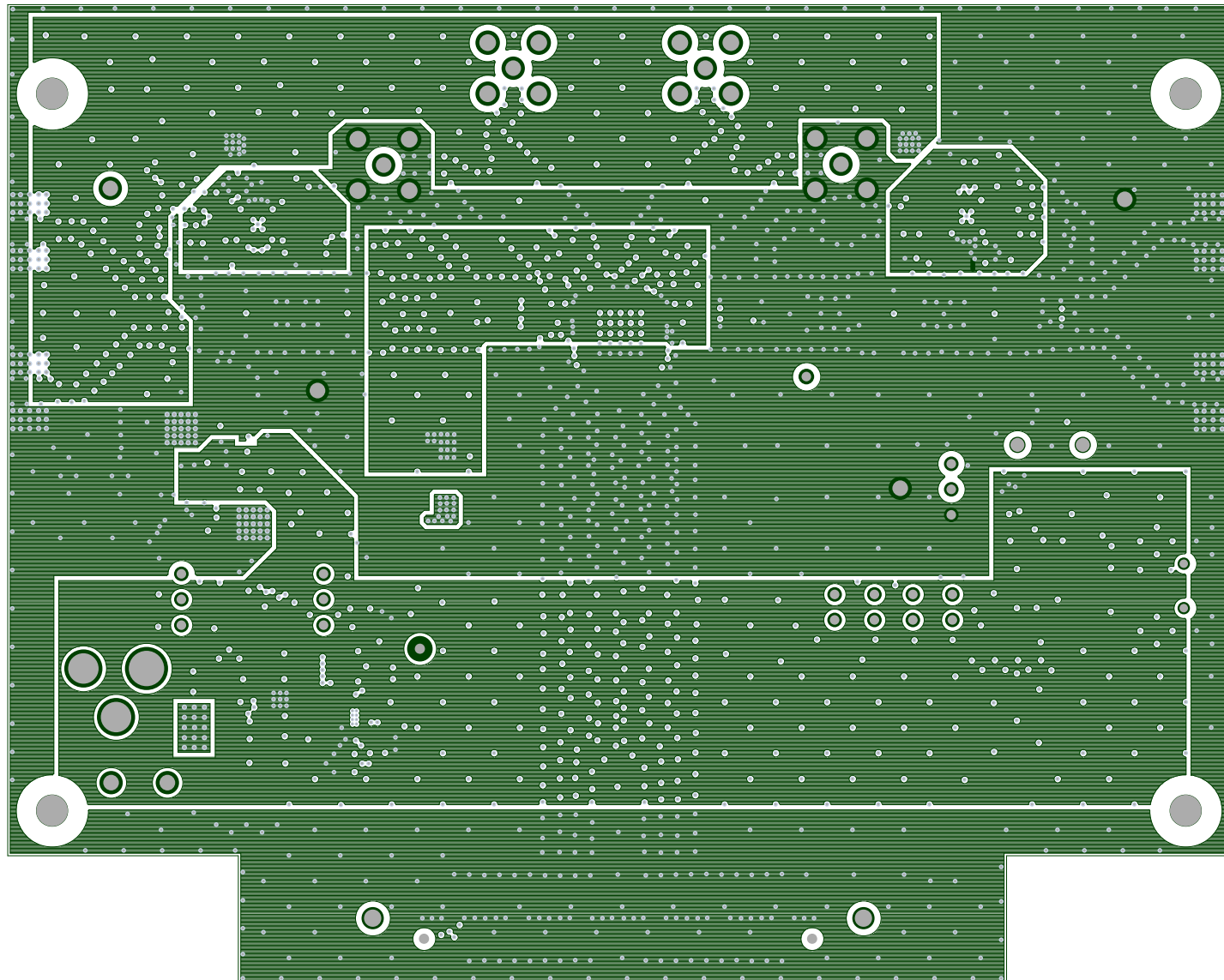
TEXAS INSTRUMENTS  
ADC32XXEVM REV C

LAYER 2 - GROUND PLANE



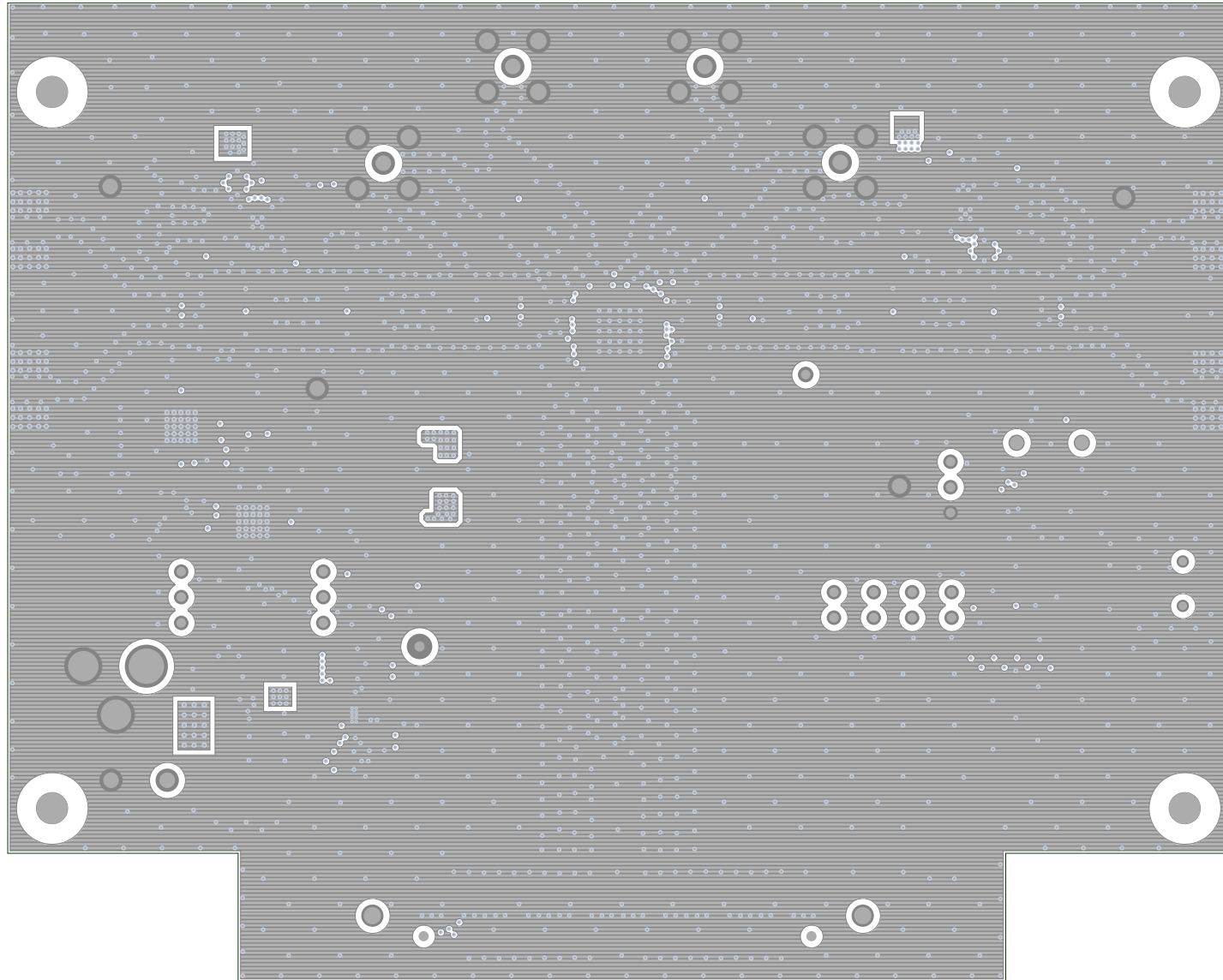
TEXAS INSTRUMENTS  
ADC32XXEVM REV C

LAYER 3 - POWER PLANE



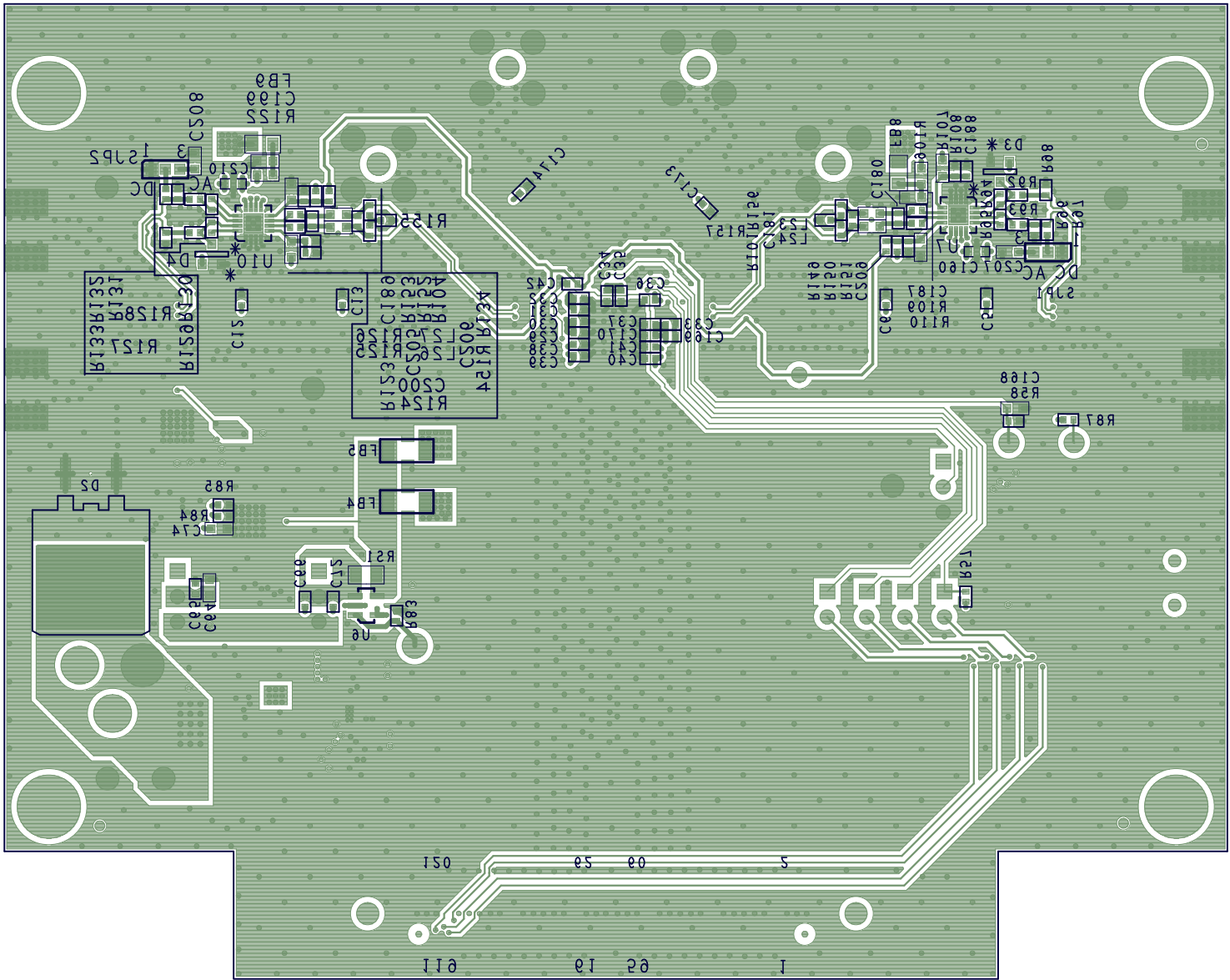
TEXAS INSTRUMENTS  
ADC32XXEVM REV C

LAYER 4 - POWER PLANE



TEXAS INSTRUMENTS  
ADC32XXEVM REV C

LAYER 5 - GROUND PLANE



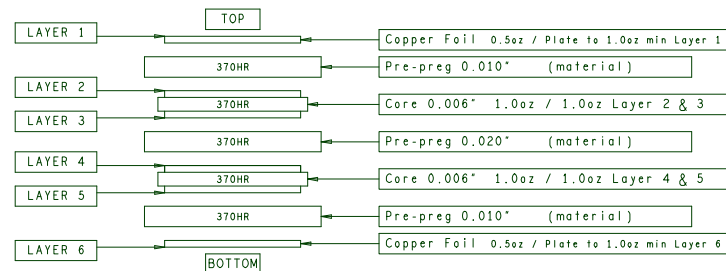
TEXAS INSTRUMENTS  
ADC32XXEVM REV C

SILKSCREEN BOTTOM SIDE

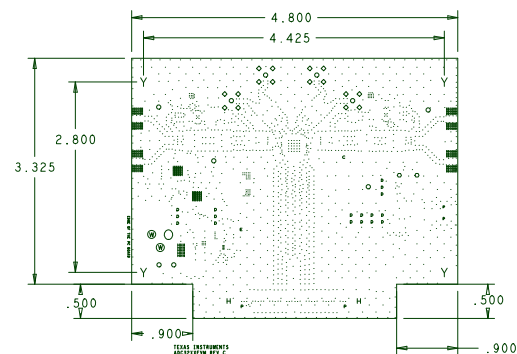
2			1		
REVISIONS					
ZONE	LTR	DESCRIPTION		DATE	APPROVED

UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.

1. APPLICATION DESIGN, MANUFACTURING AND INSPECTION DOCUMENTS  
IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES  
IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD  
IPC-A-6000 / ACCEPTABILITY OF PRINTED BOARDS.
2. HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE +/- .003.
3. REGISTRATION TOLERANCE: ARTWORK +/- .002  
ALL HOLE CENTERS +/- .005 FROM DIMENSION DATUM.
4. MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH.  
FOR ALL PLATING THROUGH HOLES. BREAKOUT NOT ALLOWED.
5. PROCESS AND MATERIAL MUST CONFORM TO UL 796, MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.  
BOARD MATERIAL SHALL BE ISOLA FR-370HR  
BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B.  
ROHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
6. MATERIAL: MULTILAYER  
TOTAL BOARD THICKNESS: .062 +/- .006  
NUMBER OF FINISHED LAYERS: 6
7. MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN COPPER/SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
8. SOLDERMASK: HASL, COLOR - RED.
9. SILKSCREEN BOTH SIDES, USING WHITE NPI LEADFREE.  
REGISTRATION TOLERANCE TO BE +/- .005
10. P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC..
11. BOARD WARPAGE, WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
12. BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS.
13. ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.
14. ALL INNER LAYER THERMALS ON 8 AND 10MIL HOLES TO BE CHANGED TO DIRECT TIES TO THE PLANE LAYERS.
15. TOP AND BOTTOM LAYERS 19 MIL TRACES TO BE 50 OHM IMPEDANCE.  
TOP AND BOTTOM LAYERS 8.5 MIL TRACES WITH 6.5 MIL SPACING TO BE 100 OHM DIFFERENTIAL IMPEDANCE.
16. MINIMUM COPPER CONDUCTOR WIDTH IS : 5 MILS.  
MINIMUM COPPER SPACING IS: 4 MILS.
17. SMOBC/IMMERSION GOLD: 2-8 uIN OVER 118-236 uIN PLATING.
18. PADS MAY BE TEAR-DROPPED TO MEET THE ANNUAL RING REQUIREMENTS.
19. PCB MUST BE ROHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY.  
MAX REFLOW OF 260 DEGREES C ( 6 PASSES).
20. ALL 8 MIL AND 10 MIL HOLES/VIAS TO BE PLATED AND FILLED WITH NON-CONDUCTIVE EPOXY.  
21. FILLED VIAS SHALL BE PLATED AFTER FILLING AND COPLANAR.



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
•	8.0	PLATED	8
•	10.0	PLATED	1764
•	12.0	PLATED	185
•	38.0	PLATED	1
•	38.0	PLATED	17
•	40.0	PLATED	1
•	55.0	PLATED	2
•	62.0	PLATED	10
•	67.0	PLATED	16
H	68.0	PLATED	2
⊙	120.0	PLATED	2
Y	125.0	PLATED	4
O	140.0	PLATED	1
•	35.0	NON-PLATED	2
•	40.0	NON-PLATED	2



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS    DECIMALS    ANGLES +/-      .XX +/- .01      +/- .XXX +/- .005      +/-		CONTRACT NO.		TEXAS INSTRUMENTS INC.	
MATERIAL  SEE NOTE 5		APPROVALS	DATE	FABRICATION DRAWING  ADC32XXEVM	
		DRAWN L. NGUYEN	07-08-14		
		ENGR K. CHAN			
FINISH  SEE NOTES 7, 8, 9				SIZE	CODE IDENT NO. DRAWING NO.
DO NOT SCALE DRAWING				B	C
				SCALE	SHEET 1 OF 1

D

C

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